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Claim 1 has been amended and new claims 22-25 have been added to the application. Support for amendments and new claims may be found throughout the specification. No new matter has been introduced by the instant amendment.

The present invention provides polyamide resin compositions having excellent bending modulus of elasticity and heat resistance, high in degree of crystallization even at a relatively low mold temperature, capable of providing the molded products with fine visual appearance and having excellent weathering resistance which has excellent thermal and mechanical properties and surface appearance, and particularly is capable of maintaining gloss with minimized surface roughening and change of color tone even if left in an outdoor exposure environment, and the molded products of such a resin composition.

More particularly, the present invention provides polyamide resin compositions consisting essentially of:

100 parts by weight of a polyamide resin mixture comprising
(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof
and
(B) 10 to 80% by weight of an aromatic polyamide resin;
and
(C) 0 to 300 parts by weight of an inorganic filler,
said aromatic polyamide resin having diamine units comprising 10 to 50 mold of paraxylylenediamine units and 50 to 90 mold of methaxylylenediamine units, and aliphatic dicarboxylic acid units.

Claims 1, 7-13, 17-21 were rejected under 35 U.S.C. § 102(b), as being anticipated by, or in the alternative, under 35 U.S.C. §103(a) as obvious over European 0585056 (EP '056).

The rejection is traversed.

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EP 0585056 teaches a resin composition comprising as essential components: (1) an MX nylon, (2) a modified polyphenylene ether resin, (3) a fibrous inorganic filler, (4) a powdery inorganic filler, (5) an epoxy resin and (6) a copper compound and/or a powdery phenolic resin.

A modified polyphenylene ether resin is essential component of the resin composition recited by EP '056. In contrast, the resin of the present invention does not comprise polyphenylene ether resins. More particularly, polyphenylene ether resins are not an essential component of the resins of the present invention. Moreover, one skilled in the art would not have been motivated to make resins of the present invention from the teachings of EP '056. Further, it would not have been obvious to create new resins having improved weathering by eliminating the essential polyphenylene ether resin component of the composition recited in EP '056.

Thus the polyamide resin composition and improved weather resistance provided by the present invention differs from the resin composition of EP '056. Therefore, claim 1 is patentable over the disclosure of EP '056 and the polyamide resin provided by claim 1 would not have been obvious to one skilled in the art based on the disclosure of EP '056. Claims 7-13 and 17-21 depend from claim 1 and are therefore also patentable over the teachings of EP '056.

Claims 2, 3, and 16 were rejected under 35 U.S.C. §103(a) as obvious over European 0585056 (EP '056) in view of European 0839862 (EP '862).

The rejection is traversed.

The EP '862 reference fails to overcome the limitations of EP '056. As the reference is understood, EP '862 teaches a heat-aging-resistant polyamide resin composition, comprising a polyamide (A), a polyamide (B), a copper compound (D), a halide (E), hindered phenols (F), hindered amines (G) and an organophosphorus compound (H). The polyamide (A) is obtained by polymerizing a monomer containing 70 mole% or more of m-xylylenediamine as a diamine

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component and a monomer containing 70 mole% or more of adipic acid as a dicarboxylic acid as a dicarboxylic acid component.

EP '056 teaches polyamide resins comprising a polyphenylene ether as an essential component. It appears that the examiner is merely utilizing EP '862 to establish that the use of a particular ratio of para-xylylenediamine to meta-xylylene diamine in the polyamides resin compositions of EP '056 would have been obvious to one skilled in the art. However the teaching of EP '862 fails to overcome the requirement that a polyphenylene ether is an essential component of the EP '056 resin mixture.

Accordingly, claims 2, 3 and 16 are patentable over the teachings of EP '056, EP '862, or any combination thereof.

Claims 1, 7-13, and 16-21 were rejected under 35 U.S.C. § 102(b), as being anticipated by, or in the alternative, under 35 U.S.C. § 103(a) as obvious over European 0620244 (EP '244).

Claims 2, and 3 were rejected under 35 U.S.C. § 103(a) as obvious over European 0620244 (EP '244).

Each of the rejections is traversed.

EP '244 teaches biaxially stretched food packaging film having at least one layer composed of (A) a polyamide-based mixed resin containing 20 to 70 wt% of an aliphatic polyamide, (B) 5 to 35 wt% of an amorphous polyamide, (C) 5 to 45 wt% of a xylylene-based polyamide, and (D) 5 to 50 wt% of a polyamide-modified ionomer.

As the reference is understood, the biaxially stretched food packaging film recited in the EP '244 document allegedly possess excellent heat resistance, oxygen-gas barrier properties, transparency, moisture permeation resistance, flexibility, heat-shrinkable properties and toughness.

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The polyamide based resin recited by the EP '244 document **must** include between 5 and 50 weight percent of a polyamide-modified ionomer as an essential component of the resin mixture. As the reference is understood, the polyamide-modified ionomer is a mixture of a polyamide and an ethylene/acrylate copolymer in which the carboxylic acid residues of the acrylate monomer units exist as a metal salt, e.g., a metal carboxylate of zinc, lithium, potassium, magnesium, calcium, or sodium. The polyamide/poly(ethylene-co-acrylate) mixture is then heated to between 200 to 350 °C to form the polyamide modified ionomer.

In contrast, the present invention provides polyamide resin mixtures with improved weathering resistance which **consist essentially** of (1) a polyamide 6 resin, a polyamide 66 resin or mixture thereof, (2) an aromatic polyamide resin; and (3) inorganic filler. The polyamide composition provided by the present invention do not contain a polyamide modified ionomer, such as the polyamide modified ethylene-metal acrylate copolymers recited by EP '244, in the resin composition.

Moreover, EP '244 neither discloses nor suggests a polyamide resin composition of the present invention **consisting essentially** of (1) a polyamide 6 resin, a polyamide 66 resin or mixture thereof, (2) an aromatic polyamide resin; and (3) inorganic filler. Further, EP '244 neither discloses nor suggests any resin composition, including those disclosed therein or in the present invention, would possess excellent bending modulus of elasticity and heat resistance, high in degree of crystallization even at a relatively low mold temperature, capable of providing the molded products with fine visual appearance and having excellent weathering resistance which has excellent thermal and mechanical properties and surface appearance, and particularly is capable of maintaining gloss with minimized surface roughening and change of color tone even if left in an outdoor exposure environment, and the molded products of such a resin composition, that is, the aspect and technical advantages of our invention.

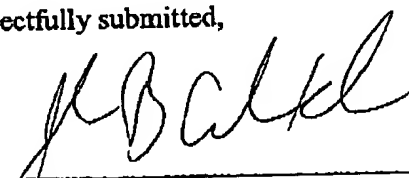
Thus the polyamide resin composition and improved weather resistance provided by the present invention differs from the resin composition of EP '244. Therefore, claim 1 is patentable

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over the disclosure of EP '244 and the polyamide resin provided by claim 1 would not have been obvious to one skilled in the art based on the disclosure of EP '244. Claims 2, 3, 7-13 and 16-21 depend from claim 1 and are therefore also patentable over the teachings of EP '244.

Although it is not believed that any additional fees are needed to consider this submission, the Examiner is hereby authorized to charge our deposit account no. 04-1105 should any fee be deemed necessary.

Respectfully submitted,



Date: January 7, 2003

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VERSION WITH MARKINGS TO SHOW CHANGES TO CLAIMS

Please note that additions to the claims are shown underlined and deletions are shown in brackets.

IN THE CLAIMS:

Kindly amend claim 1, as follows:

1. (Amended) A polyamide resin composition [comprising] consisting essentially of:
100 parts by weight of a polyamide resin mixture comprising
(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof
and
(B) 10 to 80% by weight of an aromatic polyamide resin;
and
(C) 0 to 300 parts by weight of an inorganic filler,
said aromatic polyamide resin having diamine units comprising 10 to 50 mol% of
paraxylylenediamine units and 50 to 90 mol% of methaxylylenediamine units, and aliphatic
dicarboxylic acid units.

Please add new claims 22-25, as follows:

22. (New) A polyamide resin composition according to claim 1, further consisting essentially of one or more additives selected from the group consisting of antistatic agent, coloring material, release agent, lubricant, plasticizer, nucleating agent, and stabilizers.

23. (New) A molded article produced by injection molding, which comprises a polyamide resin composition consisting essentially of:
100 parts by weight of a polyamide resin mixture comprising
(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof
and
(B) 10 to 80% by weight of an aromatic polyamide resin; and
(C) 0 to 300 parts by weight of an inorganic filler,

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said aromatic polyamide resin having diamine units comprising 10 to 50 mol% of paraxylylenediamine units and 50 to 90 mol% of methaxylylenediamine units, and aliphatic dicarboxylic acid units.

24. (New) A molded article according to claim 23, wherein the injection molding is conducted by use of a mirror-polished mold.

25. (New) A molded article according to claim 23, wherein the flexural modulus of elasticity is not less than 10 GPa at room temperature (23°C) and not less than 7 GPa at 80°C.